



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260716002.1	PCN Issued	July 17, 2026
Qualification of LFAB using qualified F65 Process Technology for select devices		Sample request deadline:	September 15, 2026
		Estimated 1st ship date:	October 15, 2026
Sample requests received after September 15, 2026 will not be supported.			

Change type(s)
Wafer Fab Site Wafer Fab Process Packing/Shipping/Labeling

PCN Details

Description of Change:					
Texas Instruments is pleased to announce the addition of LFAB using the F65 qualified process technology for the devices listed below.					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
TSMC	F021	300mm	LFAB	F65	300mm
Qual details are provided in the Qual Data Section.					
Reason for Change:		Supply continuity.			

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Review the SDP for additional information												
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table><tr><td>RoHS</td><td>REACH</td><td>Green Status</td><td>IEC 62474</td></tr><tr><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td></tr></table>	RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change				
RoHS	REACH	Green Status	IEC 62474										
☒ No Change	☒ No Change	☒ No Change	☒ No Change										
Changes to product identification resulting from this PCN:	Fab Site Information <table><tr><td>Chip Site</td><td>Chip Site Origin Code (20L)</td><td>Chip Site Country Code (21L)</td><td>Chip Site City</td></tr><tr><td>TSMC</td><td>T14</td><td>TWN</td><td>SAN JOSE</td></tr><tr><td>LFAB</td><td>LHI</td><td>USA</td><td>LEHI</td></tr></table>	Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City	TSMC	T14	TWN	SAN JOSE	LFAB	LHI	USA	LEHI
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City										
TSMC	T14	TWN	SAN JOSE										
LFAB	LHI	USA	LEHI										

Sample product shipping label (not actual product label):



Products Affected:

CC1310F128RGZR	CC1310F128RHBT	CC1310F32RHBR	CC1310F64RGZT
CC1310F128RGZT	CC1310F128RSMR	CC1310F32RHBT	CC1310F64RHBR
CC1310F128RGZT G4	CC1310F128RSMT	CC1310F32RSMR	CC1310F64RHBT
CC1310F128RHBR	CC1310F32RGZR	CC1310F32RSMT	CC1310F64RSMR
CC1310F128RHBR G4	CC1310F32RGZT	CC1310F64RGZR	CC1310F64RSMT

Qualification Report

CC13X0 Family Qual

Approve Date 11-June-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: CC13x0F128RGZR	Qual Device: CC13x0F128RHBR	Qual Device: CC13x0F128RSMR	QBS Reference: CC2640R2ERGZR	QBS Reference: CC2640R2FRSMR	QBS Reference: CC2640R2Fex	QBS Reference: CC2642B1ERGZR	QBS Reference: TMS320F28379SPTRQ
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	-	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	-	-	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-55C/125C	1000 Cycles	-	-	-	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	-	-	1/77/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	3/215/0	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	3/231/0	3/231/0	3/231/0
EDR	B3	NVM Data Retention*	150C	1000 Hours	-	-	-	-	-	-	3/231/0	3/231/0
ESD	E2	ESD CDM	-	500 Volts	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	3000 Volts	1/3/0	-	-	1/3/0	-	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JEESD78	-	1/3/0	-	-	1/3/0	-	1/3/0	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	-	-	3/90/0	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device CC13x0F128RGZR is qualified at MSL3 260C
- Qual Device CC13x0F128RHBR is qualified at MSL3 260C
- Qual Device CC13x0F128RSMR is qualified at MSL3 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JEESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- The qualification conditions stated in the table above apply to the qual device. The QBS references have either the same conditions or JEDEC-standard equivalent conditions.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2509-089

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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